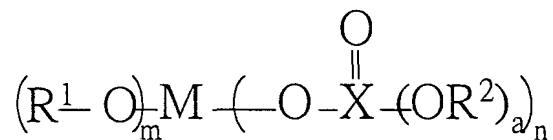


ABSTRACT OF THE DISCLOSURE

The present invention discloses a conductive composition, comprising: (a) at least one polymer; (b) at least one conductive filler, dispersed in the polymer; and (c) a coupling agent, applied to improved the adhesion between the polymer and the conductive filler and having a structure as follows:



wherein M represents a metal atom or silicon; R<sup>1</sup> and R<sup>2</sup> represent a substituted or unsubstituted alkyl group; X represents sulfur or phosphorous; and a, m and n represent integers of 0 to 2.

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